

04-14-2004

ASS



COVER SHEET

102720864

17548 U.S. PTO
10/820494



040704

4-7-04

To: Honorable Commissioner of Patents and Trademarks:

Please record the attached original document(s) or copy thereof.

1. Name of conveying party(ies)

- a) **Kishor V. Desai**
- b) **Maniam B. Alagaratnam**

2. Name and address of receiving party(ies):

- a) Name: **LSI Logic Corporation**
- Address: **1621 Barber Lane**
Milpitas, CA 95035

3. Nature of conveyance

- | | | | |
|-------------------------------------|--------------------|--------------------------|-------------------|
| <input checked="" type="checkbox"/> | Assignment | <input type="checkbox"/> | Merger |
| <input type="checkbox"/> | Security Agreement | <input type="checkbox"/> | Change of Name |
| <input type="checkbox"/> | Other _____ | <input type="checkbox"/> | License Agreement |

Execution Date: **April 7, 2004**

10820494

4. Application Number(s) or Patent Number(s): Filed Herewith

The title of the (new) application is: **METHOD AND APPARATUS FOR ESTABLISHING IMPROVED THERMAL COMMUNICATION BETWEEN A DIE AND A HEATSPREADER IN A SEMICONDUCTOR PACKAGE**

5. Please send all correspondence concerning this (these) documents to:

Customer Number: 24319

6. Total number of applications and patents involved: **1**

7. Total fee (37 CFR 3.41): **\$40.00**

- Enclosed.
- Charge to Deposit Account No. 12-2252 (Order No. 03-2198).
- Any additional fees are authorized to be charged to Deposit Account No. 12-2252 (Order No. 03-2198).

Date: April 7, 2004

Francis T. Kalinski II
Registration No. 44,177

Total number of pages including this cover sheet, attachments and documents: **2**

04/13/2004 ECDOPER 00000092 122252 10820494

01 FC:8021 40.00 DA

03-2198/LSI1P242

(Revised 12/01)

PATENT
REEL: 015196 FRAME: 0593

ASSIGNMENT

For good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, I, the undersigned, Kishor V. Desai and Manium B. Alagaratna, do hereby sell, assign, and transfer to: LSI LOGIC CORPORATION, a corporation of Delaware, having a place of business at 1621 Barber Lane, Milpitas, California 95035, ("Assignee"), its successors, assigns, and legal representatives, the entire right, title and interest for the United States and all foreign countries, in and to any and all inventions and improvements which are disclosed in the application for United States Letters Patent,

- (X) which has been executed by the undersigned concurrently herewith,
- () which was filed on _____ and assigned Application No. _____,

and is entitled: **METHOD AND APPARATUS FOR ESTABLISHING IMPROVED THERMAL COMMUNICATION BETWEEN A DIE AND A HEATSPREADER IN A SEMICONDUCTOR PACKAGE**

and in and to said application and all divisional, continuing, substitute, renewal, reissue, and all other applications for Letters Patent which have been or shall be filed in the United States and all foreign countries on any of said improvements; and in and to all original and reissued patents which have been or shall be issued in the United States and all foreign countries on said improvements; and in and to all rights of priority resulting from the filing of said United States application; and

Agree that said Assignee may apply for and receive Letters Patent for said improvements in its own name; and that, when requested, without charge to, but at the expense of, said Assignee, its successors, assigns and legal representatives, to carry out in good faith the intent and purpose of this Assignment, the undersigned will execute all divisional, continuing, substitute, renewal, reissue, and all other patent applications on any and all said improvements; execute all rightful oaths, assignments, powers of attorney and other papers; communicate to said Assignee, its successors, assigns, and representatives, all facts known to the undersigned relating to said improvements and the history thereof; and generally do everything possible which said Assignee, its successors, assigns or representatives shall consider desirable for aiding in securing and maintaining proper patent protection for said improvements and for vesting title to said improvements and all applications to patents and all patents on said improvements, in said Assignee, its successors, assigns and legal representatives; and

Covenant with said Assignee, its successors, assigns and legal representatives that no assignment, grant mortgage, license, or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

Name: Kishor V. Desai Date: 4/7, 2004
Kishor V. Desai

Witness: [Signature]
Printed

Name: Maniam B. Alagaratnam Date: 4/7, 2004
Maniam B. Alagaratnam

Witness: [Signature]
Printed